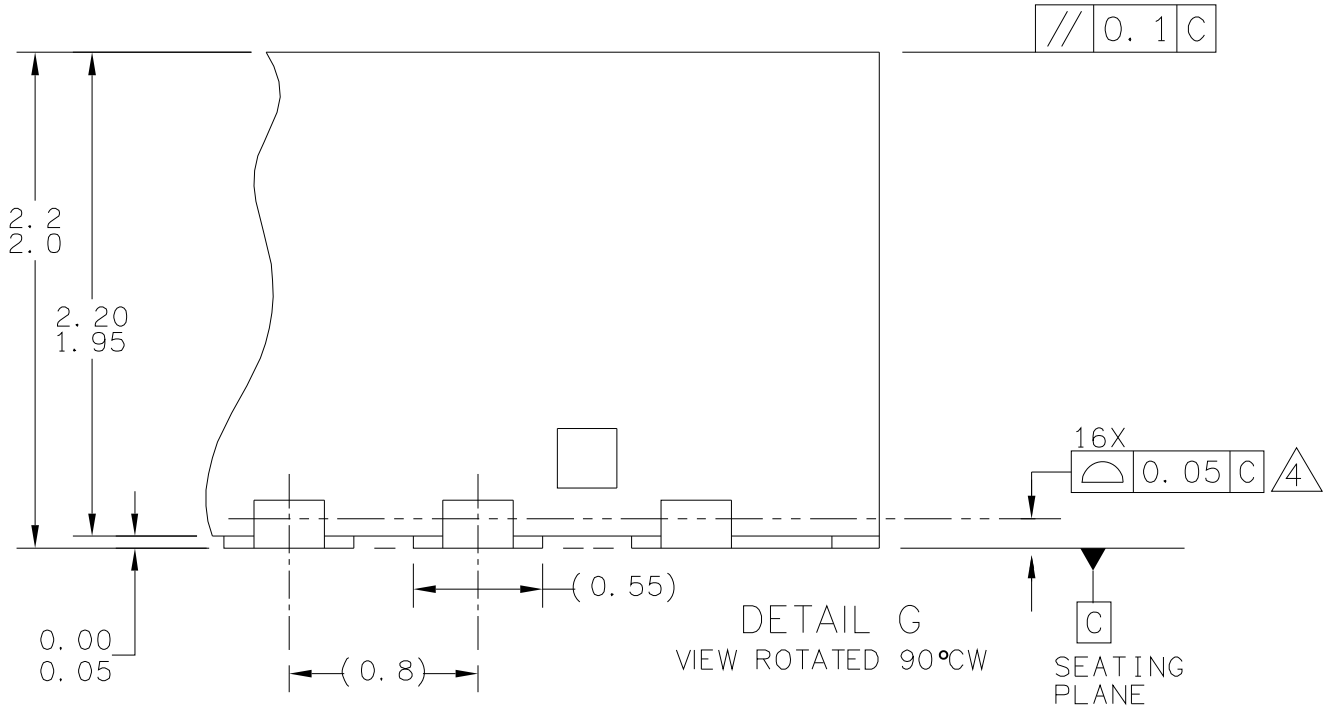
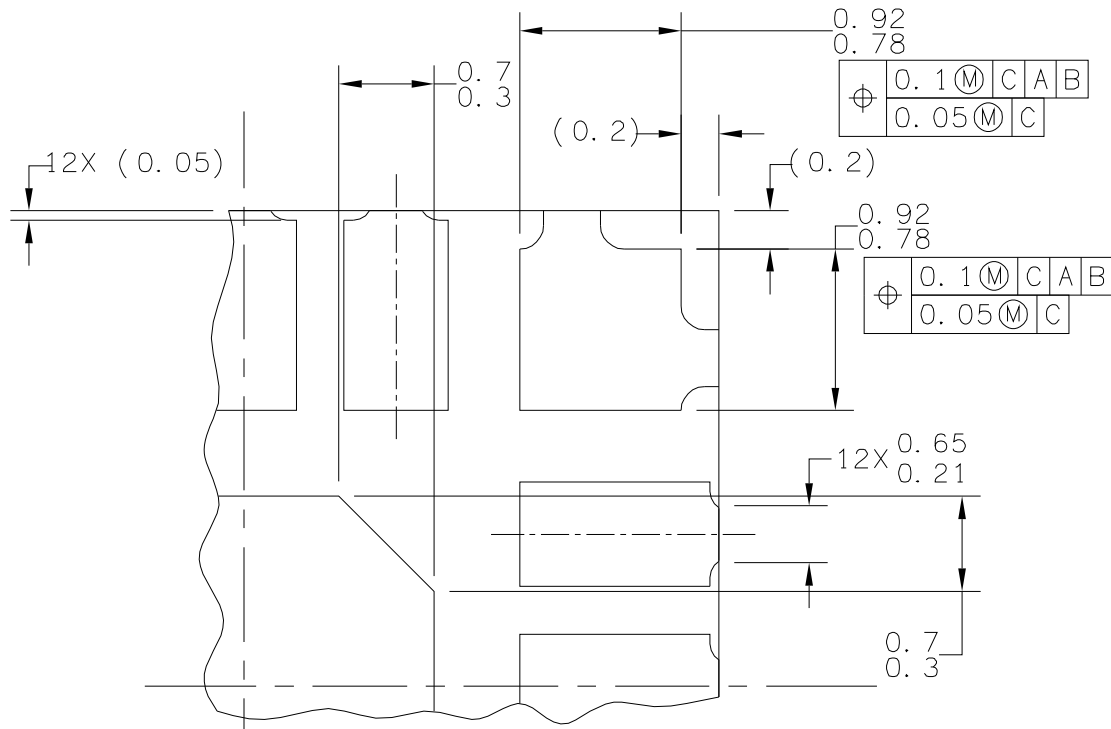


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TITLE:THERMALLY ENHANCED POWER QUAD FLAT NON-LEADED PACKAGE (PQFN) 16 TERMINAL, 0.8 PITCH (5X5X2.1) CASE OUTLINE	DOCUMENT NO: 98ARL10575D	REV: F	
	CASE NUMBER: 1543-04	19 MAY 2010	
	STANDARD: JEDEC M0-251		



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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
- △ 4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MINIMUM METAL GAP SHOULD BE 0.25MM.

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